# Advance Information **Intelligent Power Module (IPM)** 600 V, 30 A



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#### Overview

This "Inverter Power IPM" is highly integrated device containing all High Voltage (HV) control from HV-DC to 3-phase outputs in a single DIP module (Dual-In line Package). Output stage uses IGBT / FRD technology and implements Under Voltage Protection (UVP) and Over Current Protection (OCP) with a Fault Detection output flag. Internal Boost diodes are provided for high side gate boost drive.

#### **Function**

- Single control power supply due to Internal bootstrap circuit for high side pre-driver circuit
- All control input and status output are at low voltage levels directly compatible with microcontrollers
- Cross conduction prevention
- Externally accessible embedded thermistor for substrate temperature measurement
- The level of the over-current protection current is adjustable with the external resistor, "RSD"

#### Certification

• UL1557 (File Number : E339285)

#### **Specifications**

#### Absolute Maximum Ratings at Tc = 25°C

Parameter	Symbol	Remarks	Ratings	Unit
Supply voltage	V <sub>CC</sub>	P to N, surge < 500 V *1	450	V
Collector-emitter voltage	VCE	P to U, V, W or U, V, W to N	600	V
Output current	lo	P, N, U, V, W terminal current	±30	Α
Output current	10	P, N, U, V, W terminal current, Tc = 100°C	±15	A
Output peak current	lop	P, N, U, V, W terminal current, PW = 1 ms	±49	Α
Pre-driver supply voltage	VD1, 2, 3, 4	VB1 to VS1, VB2 to VS2, VB3 to VS3, $V_{DD}$ to $V_{SS}$ *2	20	V
Input signal voltage	VIN	HIN1, 2, 3, LIN1, 2, 3	$-0.3$ to $V_{\hbox{\scriptsize DD}}$	V
FAULT terminal voltage	VFAULT	FAULT terminal	$-0.3$ to $V_{\hbox{\scriptsize DD}}$	V
Maximum loss	Pd	IGBT per channel	56.8	W
Junction temperature	Tj	IGBT,FRD	150	°C
Storage temperature	Tstg		-40 to +125	°C
Operating temperature	Tc	IPM case	-20 to +100	°C
Tightening torque	MT	A screw part at use M4 type screw *3	1.17	Nm
Withstand voltage	Vis	50 Hz sine wave AC 1 minute *4	2000	VRMS

Reference voltage is N terminal =  $V_{SS}$  terminal voltage unless otherwise specified.

- \*1: Surge voltage developed by the switching operation due to the wiring inductance between the P and N terminals.
- \*2 : Terminal voltage : VD1 = VB1 to VS1, VD2 = VB2 to VS2, VD3 = VB3 to VS3, VD4 =  $V_{DD}$  to  $V_{SS}$ .
- \*3: Flatness of the heat-sink should be 0.25 mm and below.
- \*4: Test conditions: AC 2500 V, 1 s.

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed. damage may occur and reliability may be affected.

This document contains information on a new product. Specifications and information herein are subject to change without notice.

#### ORDERING INFORMATION

See detailed ordering and shipping information on page 14 of this data sheet.

### Electrical Characteristics at Tc = 25°C, VD1, VD2, VD3, VD4 = 15 V

Devenuetes	Currelle el	Condi	4:	Test		Ratings		Unit
Parameter	Symbol	Conditions		circuit	Min.	Тур.	Max.	Unit
Power output section	t .	*		+			1	
Collector to emitter cut-off current	ICE	V <sub>CE</sub> = 600 V		Fig.1	-	-	100	μA
Bootstrap diode reverse current	IR(BD)	VR(BD) = 600 V	+	g	-	-	100	μA
		Ic = 30 A	Upper side		-	1.7	2.5	
Collector to emitter saturation	V <sub>CE</sub> (sat)		Lower side	Fig.2	-	2.2	3.1	- v
voltage	VCE(Sat)	Ic = 15 A,	Upper side	1 19.2	-	1.4	-	
		Tj = 100°C	Lower side		-	1.7	-	
	VF	IF = 30 A	Upper side		-	1.8	2.7	
Diode forward voltage		II - 30 A	Lower side	Fig 2	-	2.3	3.1	V
Diode forward voltage	VF	IF = 15 A,	Upper side	Fig.3	-	1.45	-	]
		Tj = 100°C	Lower side		-	1.7	-	1
	θj-c(T) IGBT -	<del> </del>	_	1.8	_	°C/W		
Junction to case thermal resistance	θj-c(T)	FWD				2.3		°C/W
Control (Pre-driver) section	OJ-C(D)	TVVD			_	2.5	_	C/VV
Pre-drive power supply consumption		VD1, 2, 3 = 15 V			-	0.05	0.4	
current	ID	VD4 = 15 V		Fig.4	-	1.0	4.0	- mA
High level input voltage	Vin H	HIN1, HIN2, HIN;	3	-	2.5	-	-	V
Low level input voltage	Vin L	LIN1, LIN2, LIN3		_	-	_	0.8	V
Logic 1 input leakage current	I <sub>IN+</sub>	VIN = +3.3 V		1		100	195	μA
Logic 0 input leakage current	I <sub>IN</sub> -	VIN = 0 V				100	1	μΑ
Protection section	-11/4-	VIII 0 V					'	μπ
Over-current protection electric current	ISD	PW = 100 μs, RSD = 0 Ω		Fig.5	37	-	49	А
V <sub>DD</sub> and V <sub>Bx</sub> supply undervoltage	V <sub>dd</sub> UV+				10.6	11.1	11.6	V
positive going input threshold	V <sub>BxUV+</sub>				10.0	11.1	11.0	, v
$V_{\mbox{\scriptsize DD}}$ and $V_{\mbox{\scriptsize Bx}}$ supply undervoltage	V <sub>dd</sub> UV-				10.4	10.9	11.4	V
negative going input threshold	V <sub>BxUV</sub> -				10.1	10.0		•
$V_{\mbox{\scriptsize DD}}$ and $V_{\mbox{\scriptsize BX}}$ supply undervoltage	VddUVH					0.2		V
I <sub>lockout</sub> hysteresis	V <sub>BxUVH</sub>							
FAULT terminal input electric current	IOSD	VFAULT = 0.1 V		-	1	1.5	-	mA
FAULT clearance delay time	FLTCLR	From time fault co	ondition clear	-	18	-	80	ms
Thermistor for substrate temperature monitor	Rt	Resistance between and VSS(20) term		-	90	-	110	kΩ
Switching character								
	tON				-	0.8	1.5	μs
Switching time	tOFF	lo = 30 A, Inducti	ve load		-	1.0	2.0	μs
Turn-on switching loss	Eon	10 - 20 4 1/	200.1/	1	-	710	-	μJ
Turn-off switching loss	Eoff	lo = 30 A, V <sub>CC</sub> =		Fig.6	-	570	-	μJ
Total switching loss	Etot	VD = 15 V, L = 690 μH			-	1280	-	μJ
Turn-on switching loss	Eon	lo = 15 A, V <sub>CC</sub> =			-	360	-	μJ
Turn-off switching loss	Eoff Etot	VD = 15 V, L = 69	90 μH,		-	460 820	-	μJ
Total switching loss  Diode reverse recovery energy	Erec	Tc = 100°C lo = 15 A, V <sub>CC</sub> =	300 V	+	-	16	-	μJ μJ
Diode reverse recovery time	Trr	VD = 15 V, L = 69 Tc = 100°C			-	62	-	ns
Reverse bias safe operating area	RBSOA	lo = 49 A, V <sub>CE</sub> =	450 V			ı Full square	e	1
Short circuit safe operating area	SCSOA	V <sub>CE</sub> = 400 V, Tc			4			μs
Electric current output signal level	ISO	lo = 30 A		-	0.384	0.405	0.427	V
					0.00	0.100	J. 12.	

Reference voltage is N terminal =  $V_{SS}$  terminal voltage unless otherwise specified.

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### Notes

1. When the internal protection circuit operates, a Fault signal is turned ON (When the Fault terminal is low level, Fault signal is ON state: output form is open DRAIN) but the Fault signal does not latch. After protection operation ends, it returns automatically within about 18 ms to 80 ms and resumes operation beginning condition. So, after Fault signal detection, set all input signals to OFF (Low) at once. However, the operation of pre-drive power supply low voltage protection (UVLO: with hysteresis about 0.2 V) is as follows.

#### Upper side:

The gate is turned off and will return to regular operation when recovering to the normal voltage, but the latch will continue till the input signal will turn 'low'.

#### Lower side

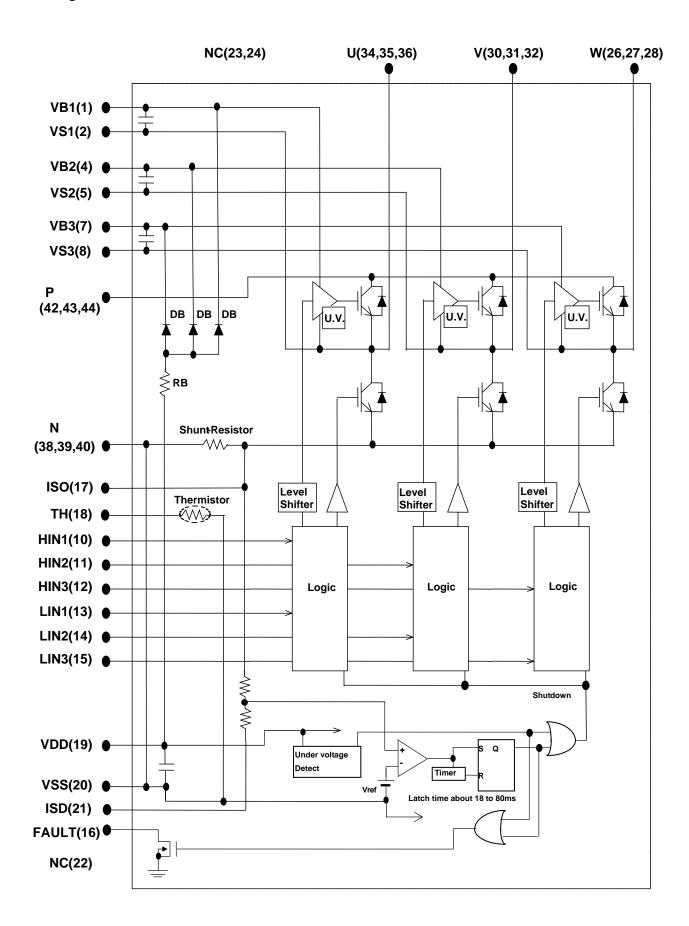
The gate is turned off and will automatically reset when recovering to normal voltage. It does not depend on input signal voltage.

- 2. When assembling the IPM on the heat sink with M4 type screw, tightening torque range is 0.79 Nm to 1.17 Nm.
- 3. The pre-drive low voltage protection is the feature to protect devices when the pre-driver supply voltage falls due to an operating malfunction.

### **Pin Assignment**

Pin No.	Name	Description	Pin No.	Name	Description
1	VB1	High side floating supply voltage 1	44	Р	Positive bus input voltage
2	VS1	High side floating supply offset voltage	43	Р	Positive bus input voltage
3	-	Without pin	42	Р	Positive bus input voltage
4	VB2	High side floating supply voltage 2	41	-	Without pin
5	VS2	High side floating supply offset voltage	40	N	Negative bus input voltage
6	-	Without pin	39	N	Negative bus input voltage
7	VB3	High side floating supply voltage 3	38	N	Negative bus input voltage
8	VS3	High side floating supply offset voltage	37	-	Without pin
9	-	Without pin	36	U	U-phase output
10	HIN1	Logic input high side driver-Phase1	35	U	U-phase output
11	HIN2	Logic input high side driver-Phase2	34	U	U-phase output
12	HIN3	Logic input high side driver-Phase3	33	-	Without pin
13	LIN1	Logic input low side driver-Phase1	32	V	V-phase output
14	LIN2	Logic input low side driver-Phase2	31	V	V-phase output
15	LIN3	Logic input low side driver-Phase3	30	V	V-phase output
16	FAULT	Fault out (open drain)	29	-	Without pin
17	ISO	Current monitor pin	28	W	W-phase output
18	TH	Thermistor out	27	W	W-phase output
19	VDD	+15 V main supply	26	W	W-phase output
20	VSS	Negative main supply	25	-	Without pin
21	ISD	Over-current protection level setting pin	24	NC	-
22	NC	-	23	NC	-

## **Block Diagram**



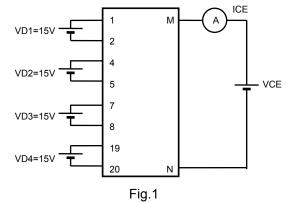
## **Test Circuit**

(The tested phase : U+ shows the upper side of the U phase and U- shows the lower side of the U phase)

## ■ ICE / IR(BD)

	U+	V+	W+	U-	V-	W-
М	42	42	42	34	30	26
N	34	30	26	38	38	38

	U(BD)	V(BD)	W(BD)
M	1	4	7
N	20	20	20



## ■ V<sub>CE</sub>(sat) (Test by pulse)

	U+	V+	W+	U-	V-	W-
М	42	42	42	34	30	26
N	34	30	26	17	19	21
m	10	11	12	13	14	15

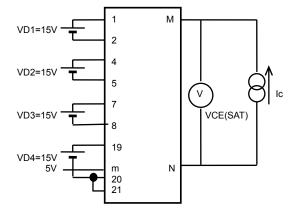


Fig.2

## ■ VF (Test by pulse)

	U+	V+	W+	U-	V-	W-
M	42	42	42	34	30	26
N	34	30	26	38	38	38

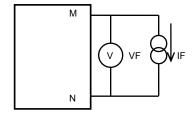


Fig.3

### ■ ID

	VD1	VD2	VD3	VD4
М	1	4	7	19
N	2	5	8	20

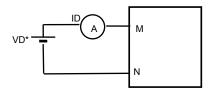
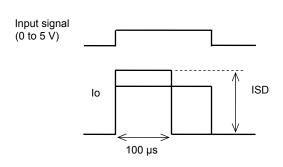


Fig.4

#### ■ ISD



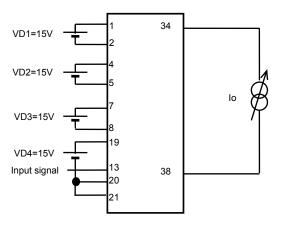
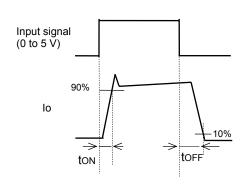
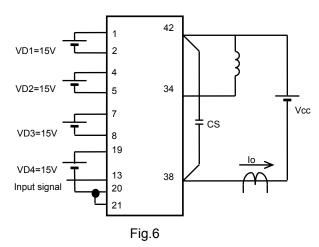


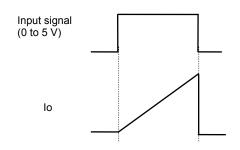
Fig.5

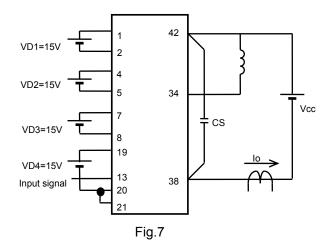
### ■ Switching time (The circuit is a representative example of the lower side U phase)





■ RB-SOA (The circuit is a representative example of the lower side U phase)





## **Logic Timing Chart**

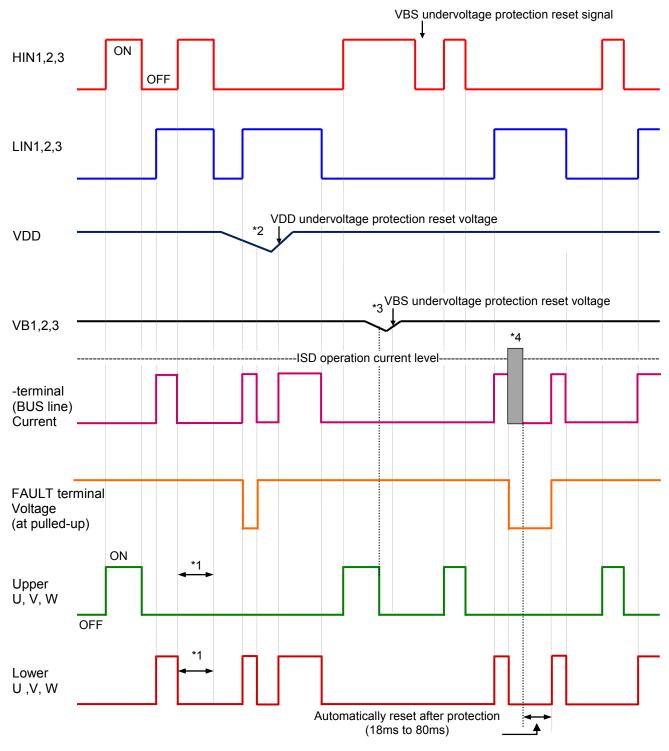
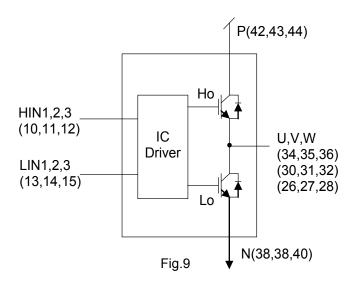


Fig. 8

#### **Notes**

- \*1: Diagram shows the prevention of shoot-through via control logic. More dead time to account for switching delay needs to be added externally.
- \*2: When V<sub>DD</sub> decreases all gate output signals will go low and cut off all of 6 IGBT outputs. part. When V<sub>DD</sub> rises the operation will resume immediately.
- \*3: When the upper side gate voltage at VB1, VB2 and VB3 drops only, the corresponding upper side output is turned off. The outputs return to normal operation immediately after the upper side gat voltage rises.
- \*4: In case of over current detection, all IGBT's are turned off and the FAULT output is asserted. Normal operation resumes in 18 to 80 ms after the over current condition is removed.

## Logic level table



FAULT*	HIN1,2,3	LIN1,2,3	U,V,W
1	1	0	Vbus
1	0	1	0
1	0	0	Off
1	1	1	Off
0	Х	Х	Off

<sup>\*</sup> With pullup registor

## **Application Circuit Example**

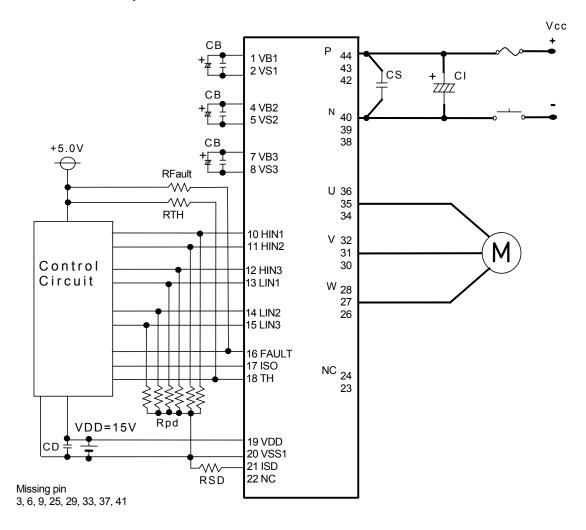


Fig.10

Recommended Operating Conditions at Tc = 25°C

Developed	Curah al	ol Conditions		Ratings		l lmi4
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Supply voltage	V <sub>CC</sub>	P to N	0	280	450	V
Pre-driver supply voltage	VD1, 2, 3	VB1 to VS1, VB2 to VS2, VB3 to VS3	12.5	15	17.5	V
Tre-driver supply voltage	VD4	V <sub>DD</sub> to V <sub>SS</sub> *1	13.5	15	16.5	v
Input ON voltage	VIN(ON)	HIN1, HIN2, HIN3,	3.0	-	$V_{DD}$	V
Input OFF voltage	VIN(OFF)	LIN1, LIN2, LIN3	0	_	0.8	ľ
PWM frequency	fPWM		1	-	20	kHz
Dead time	DT	Turn-off to turn-on (external)	2	-	-	μs
Allowable input pulse width	PWIN	ON pulse width / OFF pulse width	1	-	-	μs
Tightening torque	MT	'M4' type screw	0.79	-	1.17	Nm

<sup>\*1</sup> Pre-driver power supply (VD4 = 15 ±1.5 V) must have the capacity of lo = 20 mA (DC), 0.5 A (Peak).

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

#### **Usage Precautions**

- 1. This IPM includes bootstrap diode and resistors. Therefore, by adding a capacitor "CB", a high side drive voltage is generated; each phase requires an individual bootstrap capacitor. The recommended value of CB is in the range of 1 to 47 μF, however this value needs to be verified prior to production. If selecting the capacitance more than 47 μF (±20%), connect a resistor (about 20 Ω) in series between each 3-phase upper side power supply terminals (VB1, 2, 3) and each bootstrap capacitor.
  - When not using the bootstrap circuit, each upper side pre-drive power supply requires an external independent power supply.
- 2. It is essential that wirning length between terminals in the snubber circuit be kept as short as possible to reduce the effect of surge voltages. Recommended value of "CS" is in the range of 0.1 to 10  $\mu$ F.
- 3. "ISO" (pin 17) is terminal for current monitor. When the pull-down resistor is used, please select it more than 5.6 kΩ.
- 4. "FAULT" (pin 16) is open DRAIN output terminal. (Active Low). Pull up resistor is recommended more than 5.6 kΩ.
- 5. Inside the IPM, a thermistor used as the temperature monitor for internal subatrate is connected between VSS terminal and TH terminal, therefore, an external pull up resistor connected between the TH terminal and an external power supply should be used. The temperature monitor example application is as follows, please refer the Fig.11, and Fig.12 below.
- 6. The pull down resistor of 33 k $\Omega$  is provided internally at the signal input terminals. An external resistor of 2.2 k $\Omega$  to 3.3 k $\Omega$  should be added to reduce the influence of external wiring noise.
- 7. The over-current protection feature is not intended to protect in exceptional fault condition. An external fuse is recommended for safety.
- 8. When "N" and "V<sub>SS</sub>" terminal are short-circuited on the outside, level that over-current protection (ISD) might be changed from designed value as IPM. Please check it in your set ("N" terminal and "V<sub>SS</sub>" terminal are connected in IPM).
- The over-current protection function operates normally when an external resistor RSD is connected between ISD and V<sub>SS</sub> terminals. Be sure to connect this resistor. The level of the overcurrent protection can be changed according to the RSD value.
- 10. When input pulse width is less than 1.0 µs, an output may not react to the pulse. (Both ON signal and OFF signal)

This data shows the example of the application circuit, does not guarantee a design as the mass production set.

#### The characteristic of thermistor

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
Resistance	R <sub>25</sub>	Tc = 25°C	97	100	103	kΩ
Resistance	R <sub>100</sub>	Tc = 100°C	4.93	5.38	5.88	kΩ
B-Constant (25 to 50°C)	В		4165	4250	4335	K
Temperature Range			-40		+125	°C

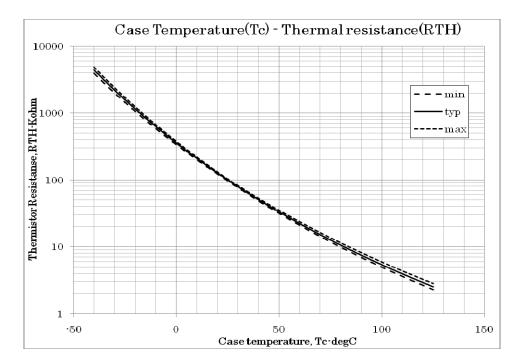


Fig.11 Variation of thermistor resistance with temperature

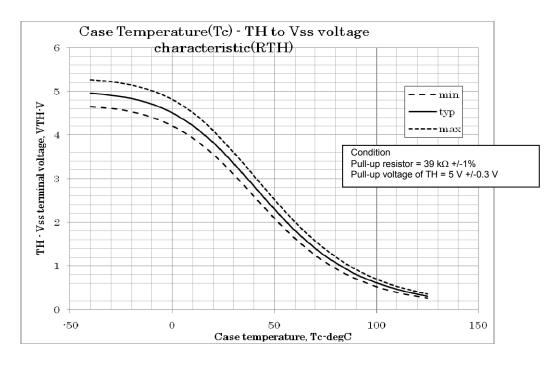


Fig.12 Variation of temperature sense voltage with thermistor temperature

### **Maximum Phase current**

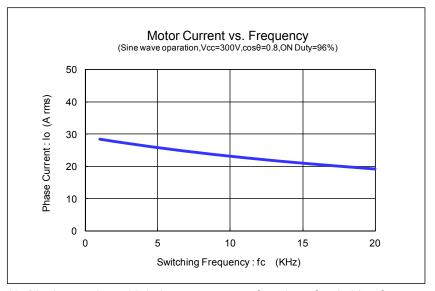


Fig.13 Maximum sinusoidal phase current as function of switching frequency at Tc = 100 °C,  $V_{CC} = 300$  V

## **Switching waveform**

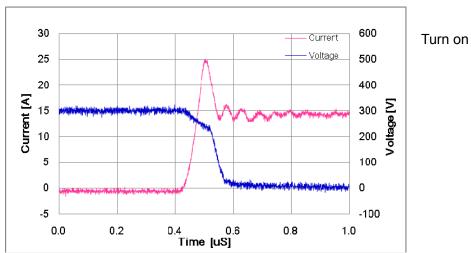


Fig. 14 IGBT Turn-on. Typical turn-on waveform at Tc =  $100^{\circ}$ C,  $V_{CC}$  = 300 V, Ic = 15 A

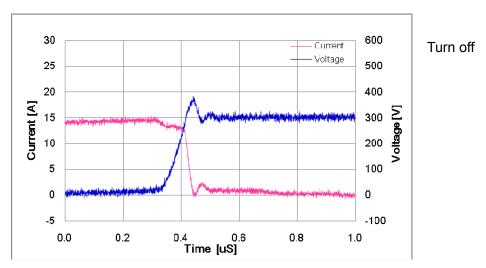


Fig. 15 IGBT Turn-off. Typical turn-off waveform  $Tc = 100^{\circ}C$ ,  $V_{CC} = 300 \text{ V}$ , Ic = 15 A

### CB capacitor value calculation for bootstrap circuit

#### **Calculate condition**

Item	Symbol	Value	Unit
Upper side power supply	VBS	15	V
Total gate charge of output power IGBT at 15 V	Qg	0.266	μC
Upper side power supply low voltage protection	UVLO	12	V
Upper side power dissipation	IDmax	400	μΑ
ON time required for CB voltage to fall from 15 V to UVLO	Ton-max	_	S

### Capacitance calculation formula

CB must not be discharged below to the upper limit of the UVLO - the maximum allowable on-time (Ton-max) of the upper side is calculated as follows :

The relationship between Ton-max and CB becomes as follows. CB is recommended to be approximately 3 times the value calculated above. The recommended value of CB is in the range of 1 to 47  $\mu$ F, however, the value needs to be verified prior to production.

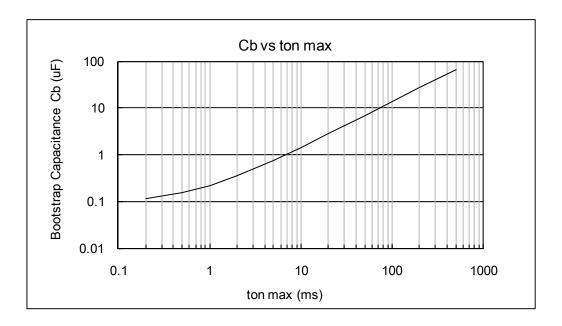


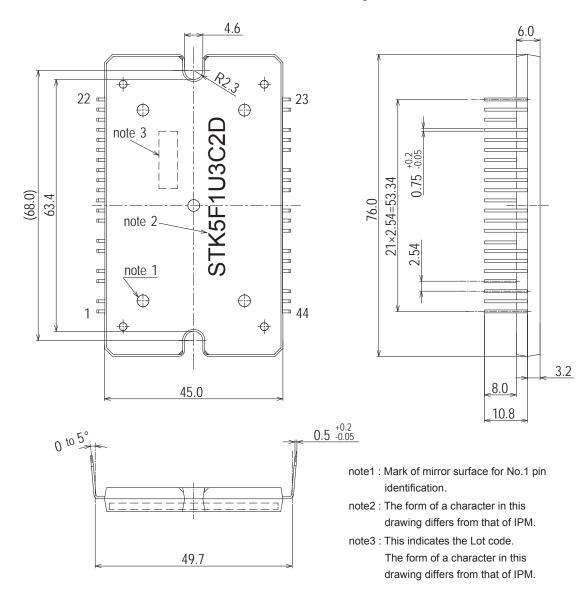
Fig.16 Ton-max vs CB characteristic

### **PACKAGE DIMENSIONS**

unit: mm

## **TENTATEIVE**

Missing Pin: 3, 6, 9, 25, 29, 33, 37, 41



### **ORDERING INFORMATION**

Device	Package	Shipping (Qty / Packing)
STK5F1U3C2D-E	TBD (Pb-Free)	6 / Tube

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